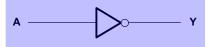
## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	-0.5	V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)		±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)		±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )		±25 mA
Continuous current through V <sub>CC</sub> or GND		±50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D package		86°C/W
N package		80°C/W
NS package		76°C/W
PW package	1	I13°C/W
Storage temperature range, T <sub>stg</sub> –	65°C t	o 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

## recommended operating conditions (see Note 3)

			S	SN54HC04		SN74HC04		LINUT		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		2	5	6	2	5	6	V	
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5			1.5			V	
		V <sub>CC</sub> = 4.5 V	3.15			3.15				
		V <sub>CC</sub> = 6 V	4.2			4.2				
VIL	Low-level input voltage	V <sub>CC</sub> = 2 V			0.5			0.5	V	
		V <sub>CC</sub> = 4.5 V			1.35			1.35		
		V <sub>CC</sub> = 6 V			1.8			1.8		
٧ı	Input voltage		0		VCC	0		VCC	V	
٧o	Output voltage		0		VCC	0		VCC	V	
Δt/Δν	Input transition rise/fall time	V <sub>CC</sub> = 2 V			1000			1000	ns	
		V <sub>CC</sub> = 4.5 V			500			500		
		V <sub>CC</sub> = 6 V			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.